

1 **DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION**

2 As the below named inventor, I hereby declare that:

3 My residence, post office address and citizenship are as stated below
4 next to my name.

5 I believe I am the original, first and joint inventor of the subject matter
6 which is claimed and for which a patent is sought on the invention entitled:
7 Conductive Connection Forming Methods, Oxidation Reducing Methods, and
8 Integrated Circuits Formed thereby, Serial No. 09/518,511, filed March 3, 2000.

9 I hereby state that I have reviewed and understand the contents of the
10 above-identified specification, including the claims.

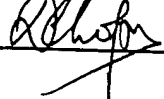
11 I acknowledge the duty to disclose information known to me to be
12 material to patentability as defined in Title 37, Code of Federal Regulations
13 §1.56.

14 **PRIOR FOREIGN APPLICATIONS:**

15 I hereby state that no applications for foreign patents or inventor's
16 certificates have been filed prior to the date of execution of this declaration.

17 I hereby declare that all statements made herein of my own knowledge
18 are true and that all statements made on information and belief are believed
19 to be true; and further that these statements were made with the knowledge
20 that willful false statements and the like so made are punishable by fine or
21 imprisonment, or both, under Section 1001 of Title 18 of the United States
22 Code and that such willful false statement may jeopardize the validity of the
 application or any patent issued therefrom.

Full name of inventor: Dinesh Chopra

Inventor's Signature: 

Date: 7/11/00

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Full name of inventor: Fred Fishburn

Inventor's Signature: 

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